

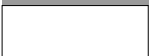




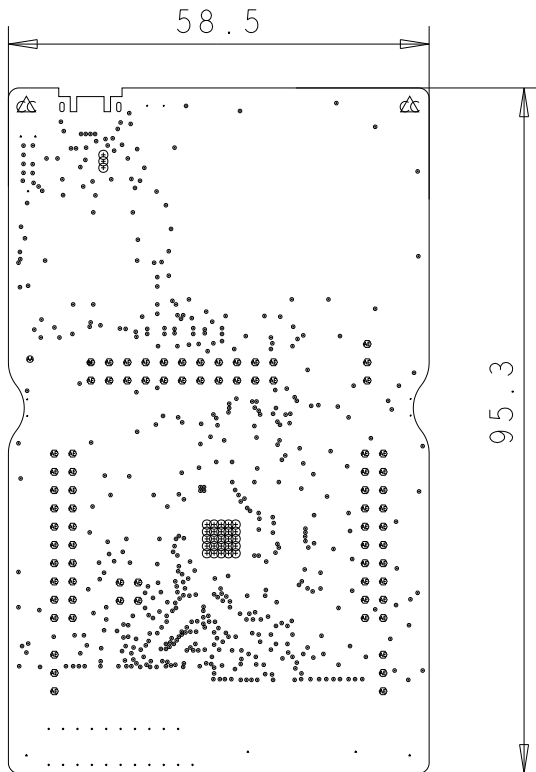


DESIGN CROSS SECTION CHART

TOTAL THICKNESS 1.6 MM

	L1: TOP CONDUCTOR - COPPER 0.035 MM
	* DIELECTRIC - FR-4 0.175 MM
	L2: L2 PLANE - COPPER 0.035 MM
	* DIELECTRIC - FR-4 1.11 MM
	L3: L3 PLANE - COPPER 0.035 MM
	* DIELECTRIC - FR-4 0.175 MM
	L4: BOTTOM CONDUCTOR - COPPER 0.035 MM



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
.	0.2	PLATED	505
⊙	0.201	PLATED	28
.	0.4	PLATED	21
•	1.05	PLATED	75
•	1.1	PLATED	1
⊕	3.2	PLATED	2
.	0.899	NON-PLATED	6
.	1.001	NON-PLATED	3
.	3.2	NON-PLATED	4
⊖	1.3x0.6	PLATED	2

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